

SRC Board Retreat 2009

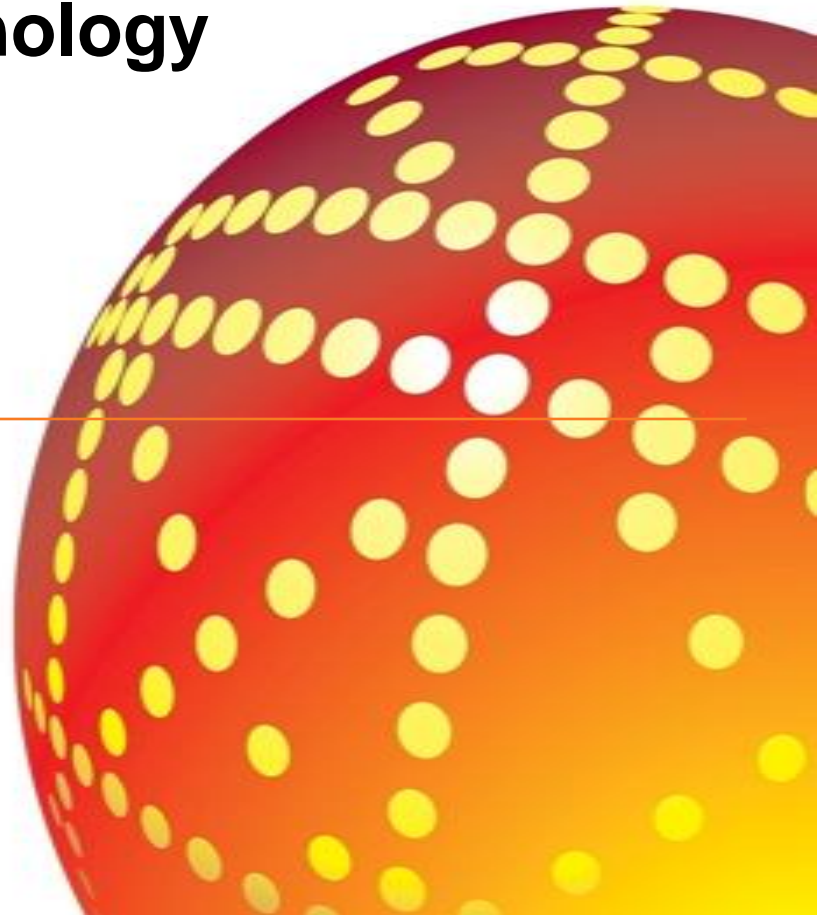
Research Opportunities at the Interface of Design and Technology



GLOBALFOUNDRIES

Mojoy Chian
SVP, Design Enablement
July, 2009

Confidential





Agenda

- **Industry landscape**
- **The race for performance (low power that is!)**
- **The race for TTM**
- **The race for lower cost**

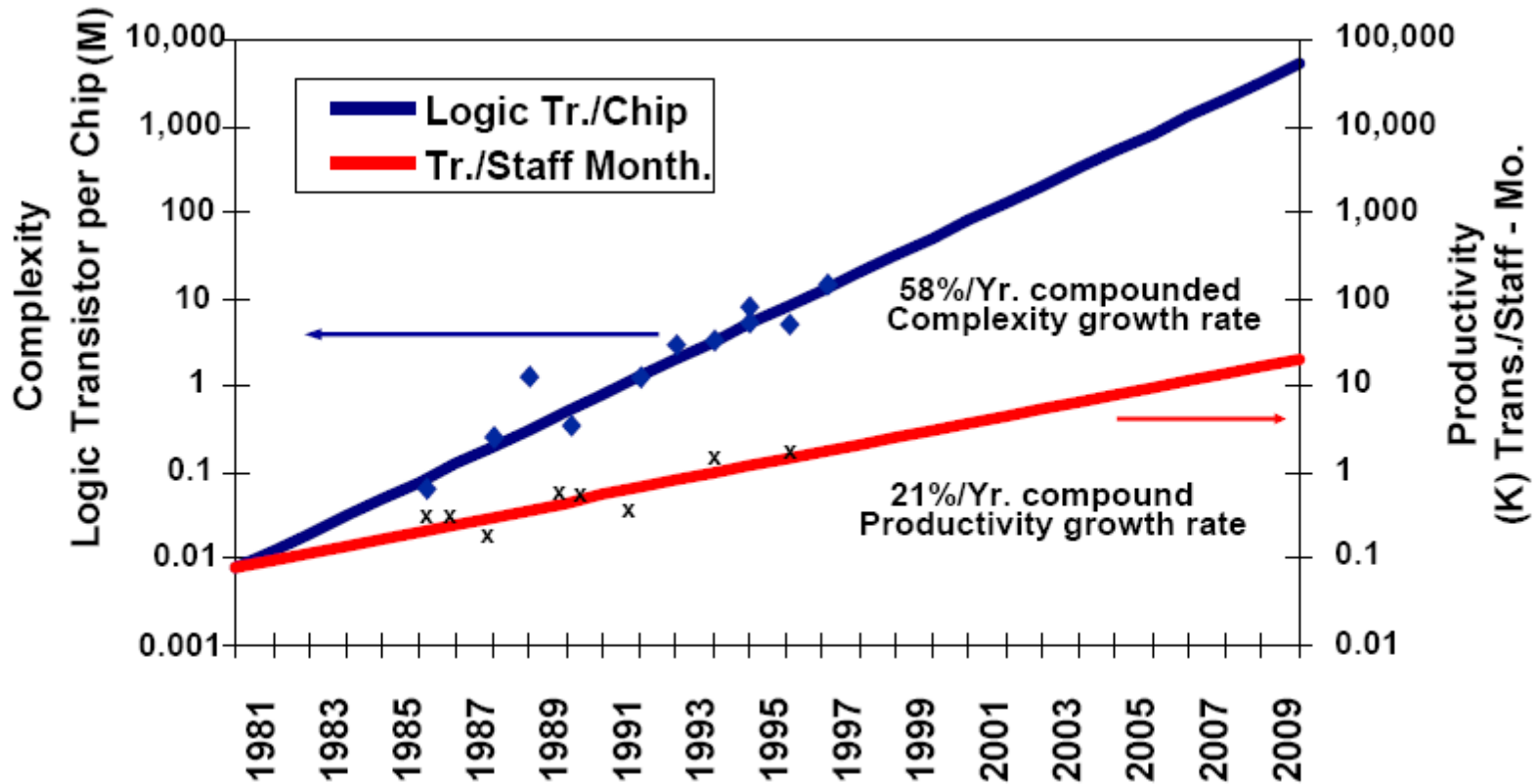
- **Research needs**
- **Conclusion**



Industry Landscape



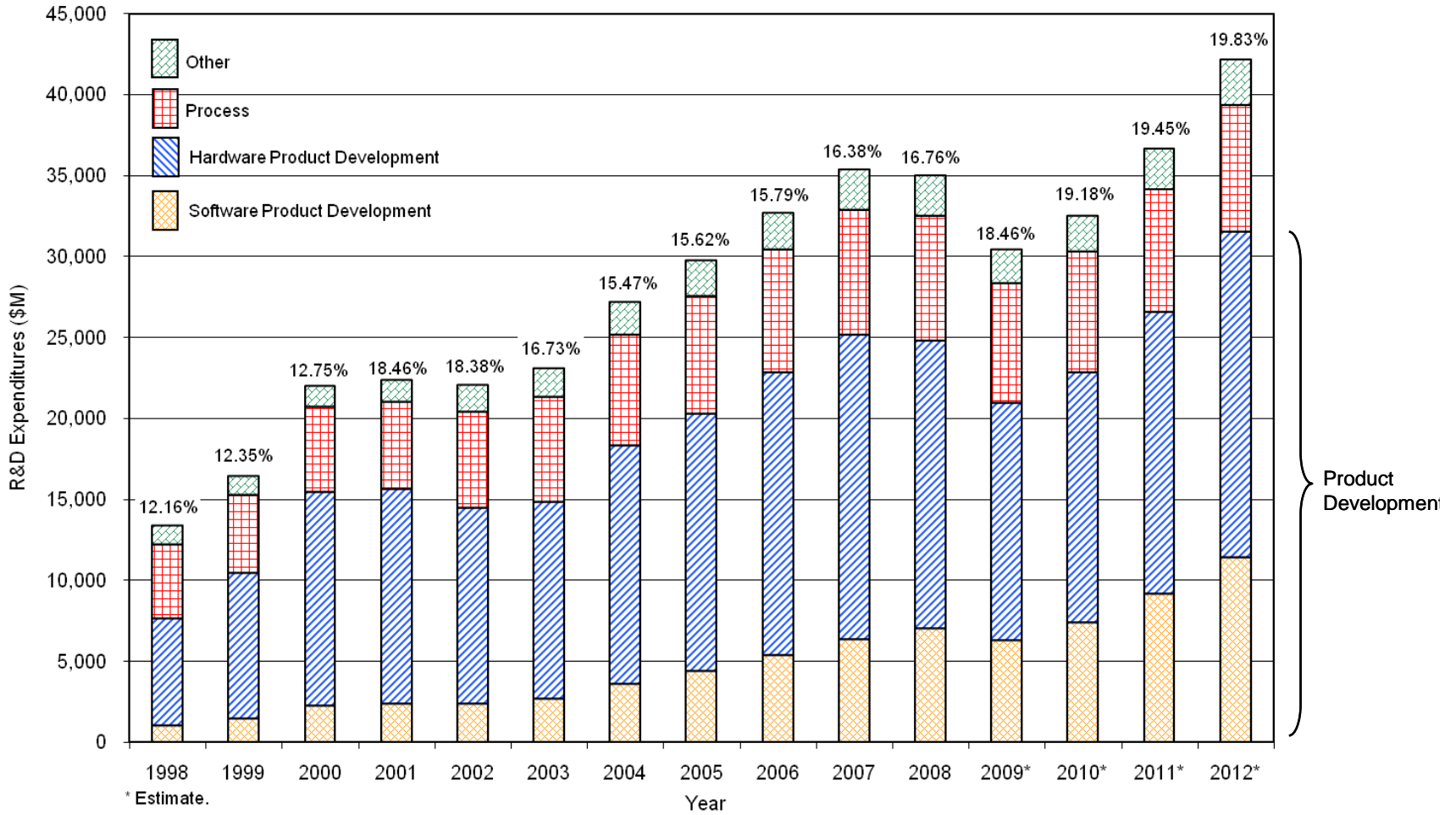
Complexity Outpaces Design Productivity



Source: Sematech



R&D Expenditures in the IC Industry



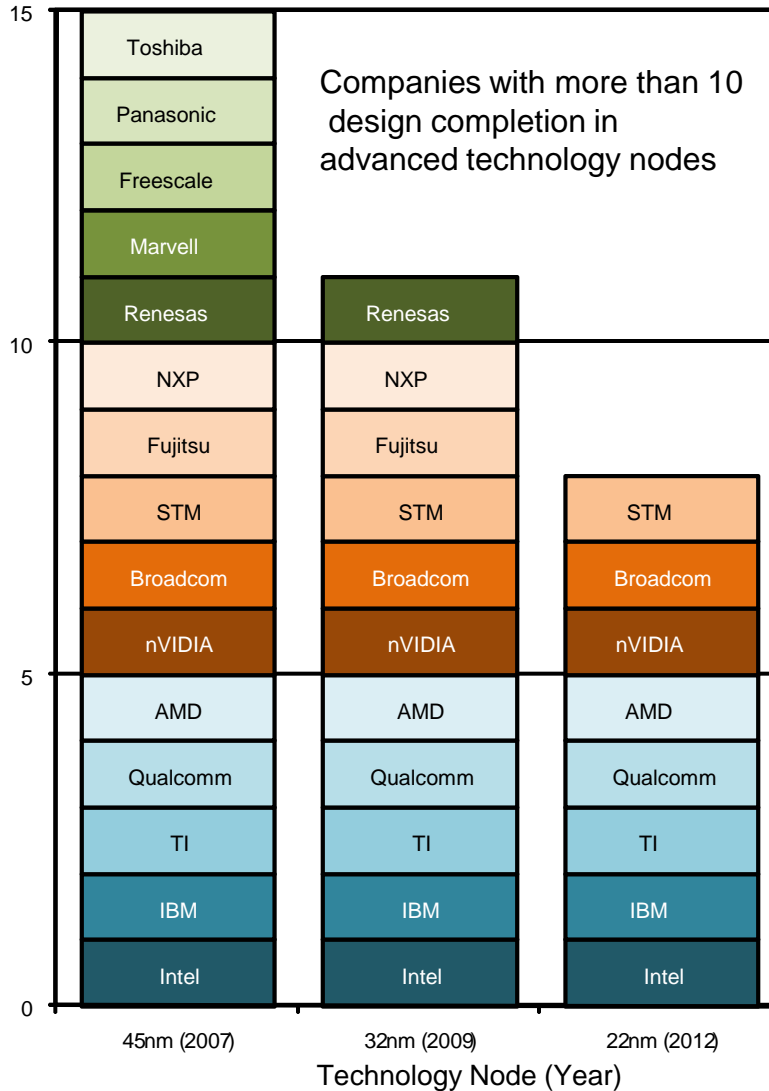


Bifurcation in Technology Adoption

- **Large IC companies are aggressively adopting new technologies**
- **Advanced technologies as a major competitive advantage**
 - **Primarily to reduce cost per function**
- **Bifurcation in technology adoption**
 1. **An elite club on an aggressive technology adoption model**
 2. **The median of ASIC starts is still at 130nm & 90nm**



Declining leading edge product designs?

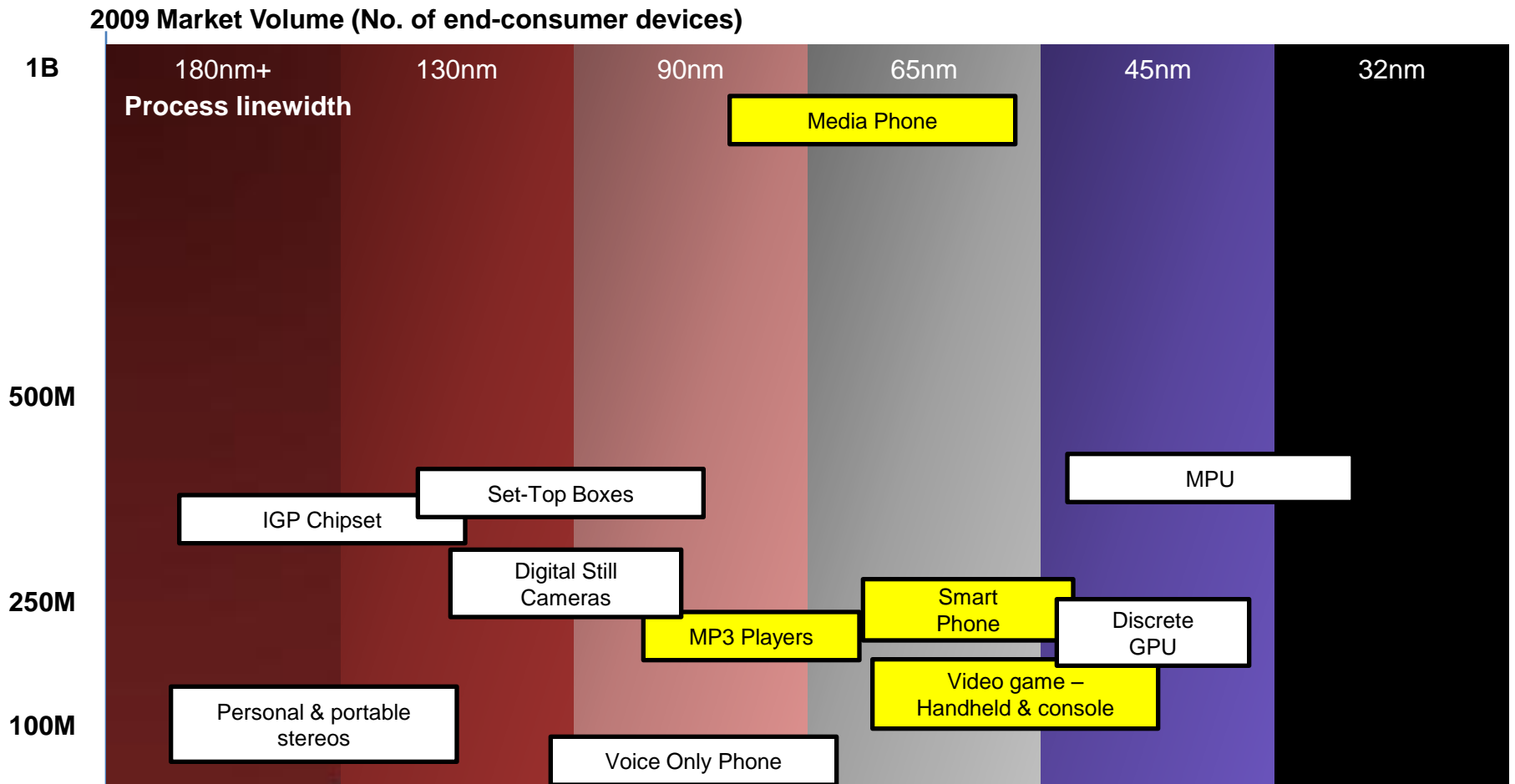


Source: IBS

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Volume at advanced technologies is increasing



Source: Bridge & GLOBALFOUNDRIES analysis, iSuppli Mobile Handset Tracker; iSuppli Consumer Platforms Market Tracker, Mercury Reports GPU, Gartner Reports GPU



Foundry leading customers

- **Customer base is consolidating**
 - Big fabless IC companies are getting bigger
 - Small players are becoming less significant
- **Revenue from advanced technologies is increasing**
- **IC bets have become larger**
 - Over \$500M in R&D to move to a new node
- **Early foundry-customer engagement**
 - Read: early design-technology engagement
- **Technology-circuit analysis and trade offs to maximize value**
 - Process-design co-customization
- **Concurrent design-process development**
 - Customer specific program and interim deliverables



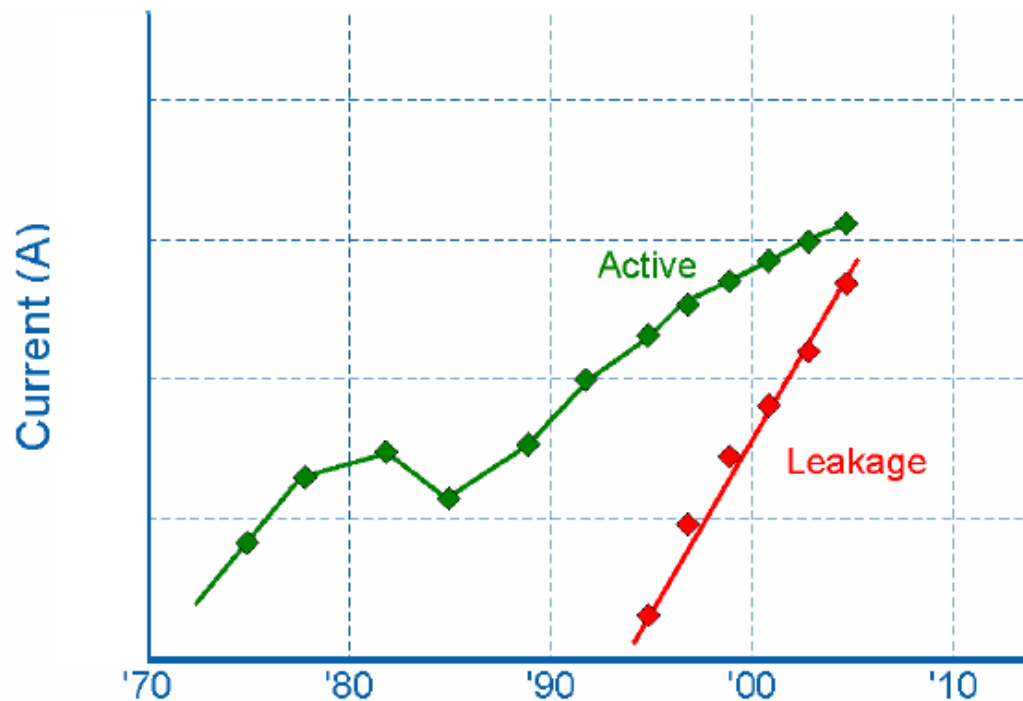
The race for performance

Design-technology co-optimization



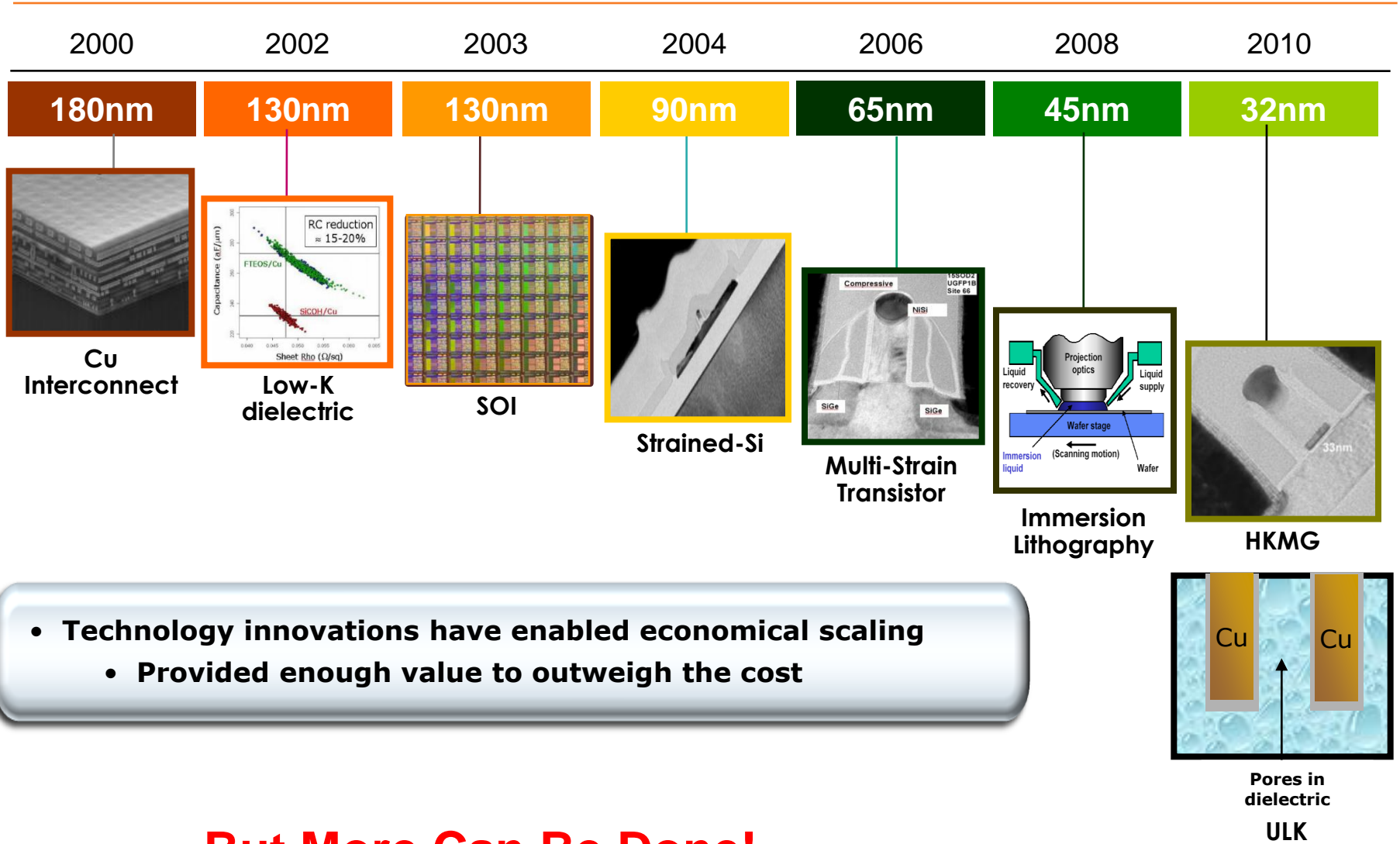
Power trend is counter scaling

- **Vcc scaling has significantly slowed down**
 - Now dropping only about 50mv per technology node
- **Smaller geometries give rise to higher leakage**





Technology Innovations



- Technology innovations have enabled economical scaling
 - Provided enough value to outweigh the cost

But More Can Be Done!



Vectors of Technology-Design Co-Optimization

1. Power - Performance co-optimization

- Moving along the universal curve to attain optimum speed-power point
 - Vcc, Vt, Lgate, back bias optimization
 - Optimizing transistors at different bias points
- Add new devices to the process

2. Design - Process Variability co-optimization

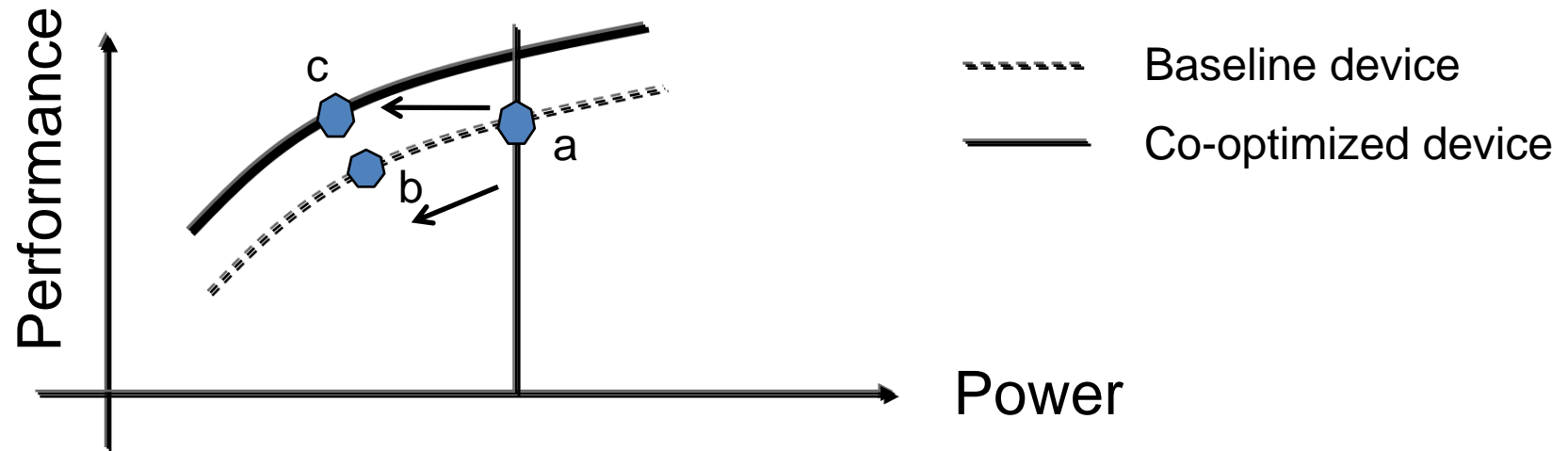
- Understand circuit margins, critical specs and their process dependency
- Co-optimize process and design to minimize guard bands for variability

3. Layout - Design Rule co-optimization

- Assess impact of design rules (or DFM rules) on layout
- Optimize layout to use a subset of design rules with minimal impact to layout



Design/Technology Co-Optimization



- **Co-optimization focuses on tuning critical device parameters to improve product performance**
 - Collaborative work between design and technology is critical
- **In most cases, this would entail moving along the universal curve (a → b)**
 - Same power-performance curve
- **But it can also reduce power at the same performance (a → c)**



A Recent Co-Optimization Example

Technology	Performance	Static Power	Total Power
Baseline Device	1	1	1
Co-Optimized Device	1.04	0.7X	1

- Equivalent of up to about $\frac{1}{4}$ node advantages can be attained by circuit-technology co-optimization

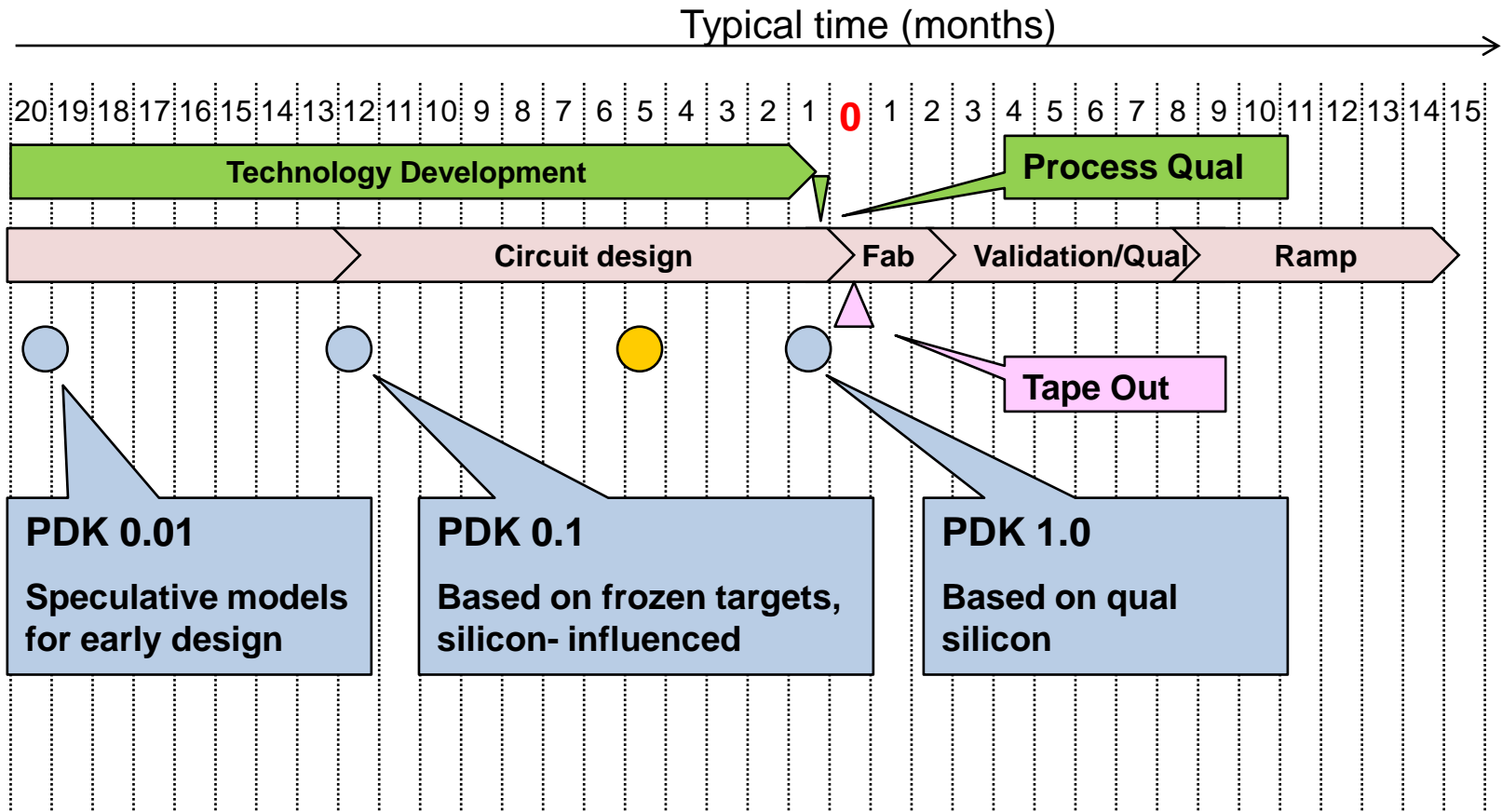


The race for TTM

Concurrent design-technology development



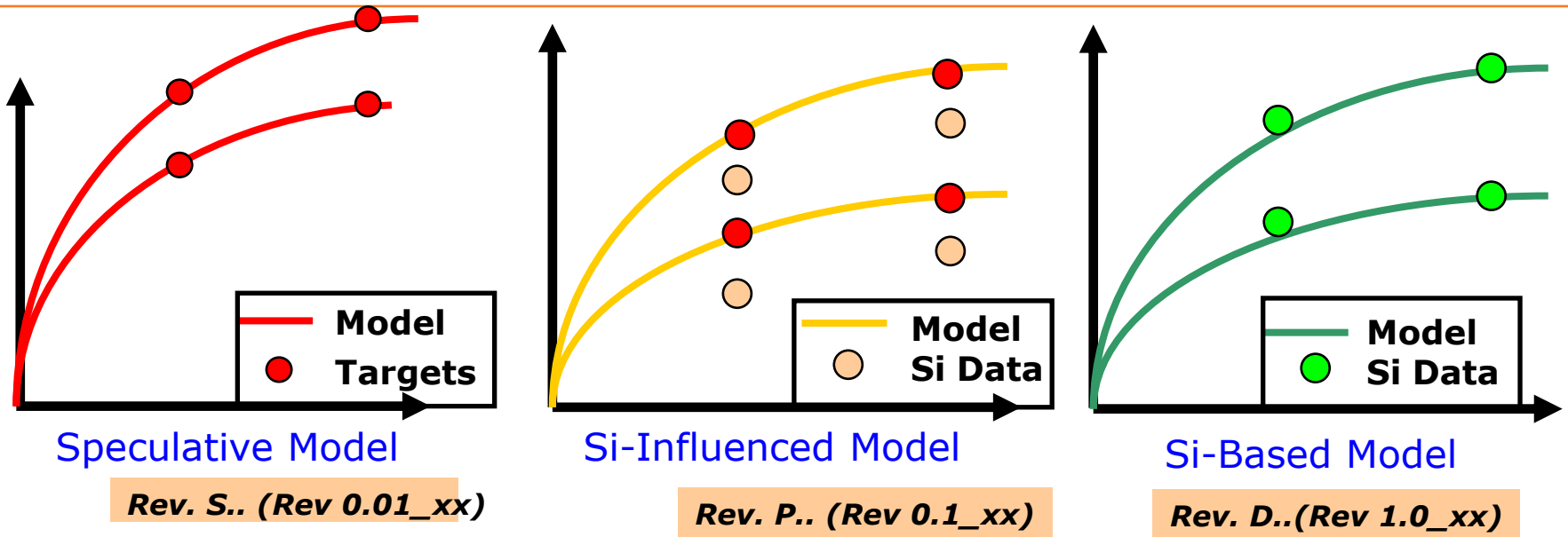
Concurrent Technology & Design Development



Source: Industry interviews and research; team analysis



SPICE Model Maturity



- **Speculative – 0.01**

- *Based on early prediction of the targets, validated with very early silicon*
- *Early design start*

- **Silicon-influenced – 0.1**

- *Based on the frozen targets, validated but does not match early silicon*
- *Design in full motion*

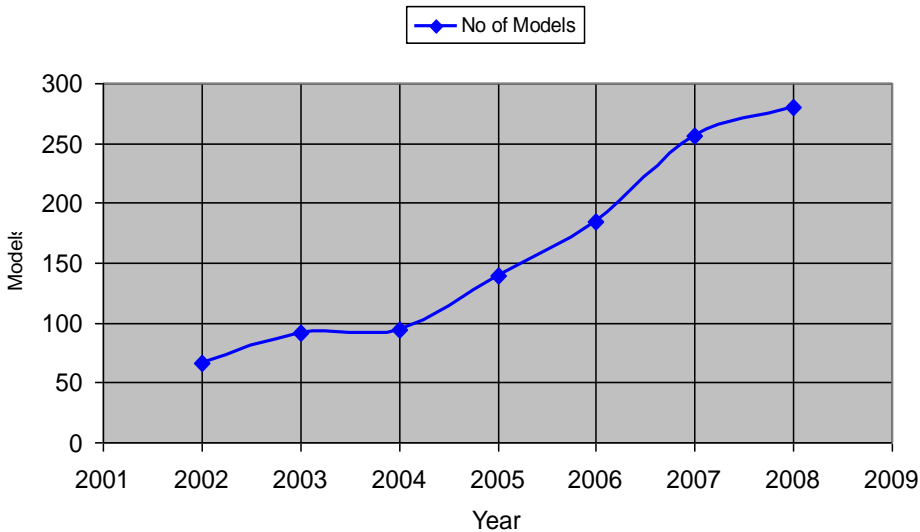
- **Silicon-based – 1.0**

- *Based on final, qual silicon*
- *Not much influence on the 1st tape out*



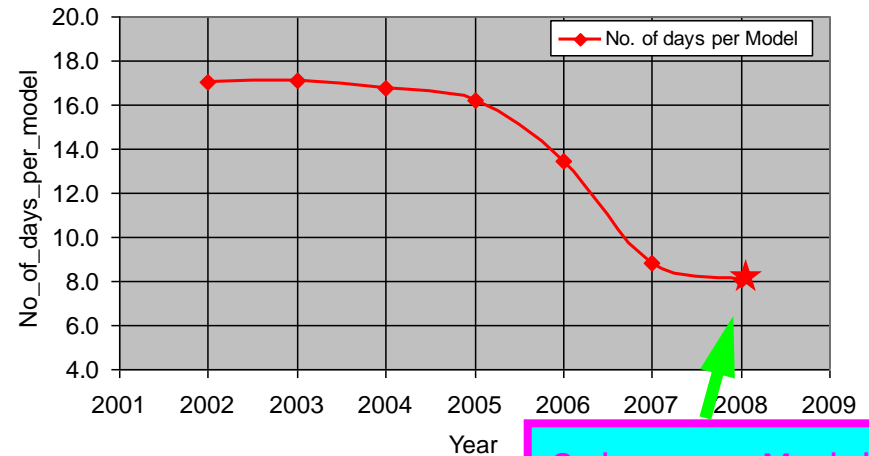
Model Extraction Efficiency Improvement

Number of Models vs. Year



Significant increase in number of models over the years

Model Efficiency (No. of Days per model) over Years



8 days per Model

Significant increase in modeling efficiency



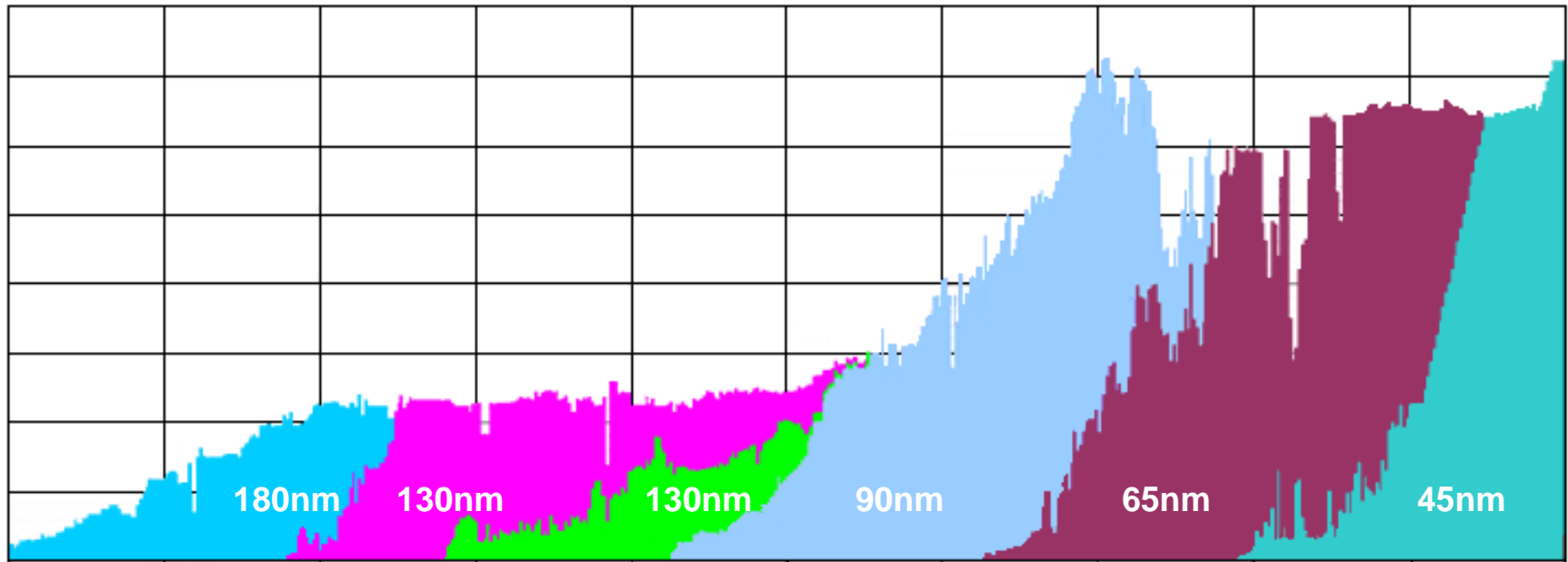
The race for lower cost

Improve yield and yield ramp



Quick Production Ramp

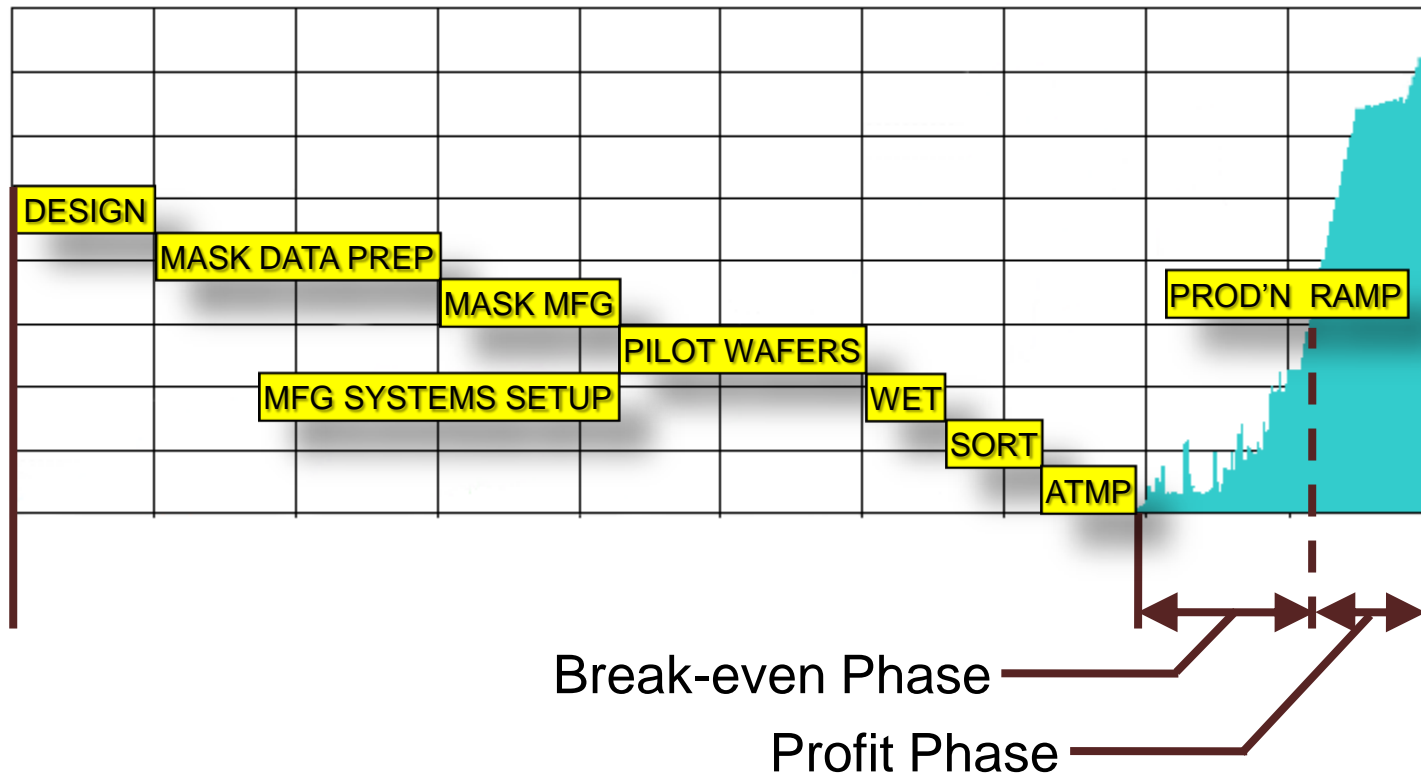
- The pace of advanced technology development continues
- With quick ramp to high volume
- Accelerated defect density reduction and yield ramp
- Emphasis on speed, accuracy, and agility across manufacturing
 - Automated Precision Manufacturing (APM)



GLOBALFOUNDRIES Production Ramp



Agility Translates into Customer Value



**Faster Cycles of Learning + Shorter Time to Mitigate Risk
Result in
Faster Time To Market & Higher ASP's for Customers**



Research Needs & Conclusion



Research Needs

- ROI necessitates maximizing value from advanced technologies
- So the race intensifies
- **Research needs:**
 - **Not a comprehensive list – but a list in support of the topic:**
 - Process technology innovations aimed at lower power
 - Target based process development and design methodology
 - Tools and methodologies for predicting device performance prior to silicon
 - Tools and methodologies for concurrent design and technology development
 - Tools and methods for fast development and assembly of tech files and PDK
 - Optimizing Restricted Design Rules (RDR) to minimize layout impact
 - Integrated DFM and impact of DFM on design and manufacturing
 - Manufacturing automation tools
 - Tools and methodologies to aid fast silicon volume ramp and fast defect density reduction



Conclusion

- **The sky is the limit**
- **Gravity is good – research needs to be connected to vectors of value**
- **Opportunities are often in the interfaces**
- **Economic trends dictate technical research directions**

